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U.S. Department of Commerce  
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**INFORMATION DISCLOSURE STATEMENT**  
**BY APPLICANT**  
(Use several sheets if necessary)

Application Number **10/082,433**  
Filing Date **2/22/2002**  
First Named Inventor **Sergey Lopatin**  
Attorney Docket No. **P1408**

Sheet 1 of 1

**U.S. PATENT DOCUMENTS**

Examiner Initial	Cite No.	U.S. Patent Document Number	Name of Patentee or Applicant of Cited Documents	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
RRK	1	6,197,181 B1	Chen, Lin Lin	3/6/2001	1
RRK	2	6,022,808	Nogami, et al.	2/8/2000	

**FOREIGN PATENT DOCUMENTS**

Examiner Initials'	Cite No.	Foreign Patent Document Office Number Code	Name of Patentee or Applicant of Cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appears

**OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS**

Examiner Initials'	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.
RRK	1	PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing", 3 <sup>rd</sup> Ed., p. 392 and 397 (1997) <b>(no month given)</b> .
RRK	2	A. Krishnamoorthy, D. Duquette and S. Murarka, "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization", in edited by Adricacos, et al., Electrochem Society Symposium Proceedings, Vol. 99-9, May 3-6, Seattle, p. 212 <b>(no year given)</b> .
RRK	3	J. Cunningham, "Using Electrochemistry to Improve Copper Interconnect", in Semiconductor International, Spring 2000 (May) <b>(no page numbers)</b> .
RRK	4	L. Chen and T. Ritzdorf, "ECD Seed Layer for Inlaid Copper Metallization" in edited by Andricacos, et al., Electrochem Society Proceedings, Vol. 99-9, May 3-6, Seattle, p. 122 <b>(no year given)</b> .

Examiner Signature: **Robt R. Koehler**

Date Considered: **March 31, 2004**

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English Language Translation is attached.

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